

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A semiconductor device comprising:
a support which is a sheet comprising a ferromagnetic material;
a binding material adjacent to the sheet comprising the ferromagnetic material;
and
an element on an insulating film adjacent to the binding material.
2. (Original) A semiconductor device according to claim 1, wherein the element is a thin film transistor, a light-emitting element having a layer containing an organic compound, an element having liquid crystal, a memory element, a thin film diode, a photoelectric transducer comprising PIN junctions of silicon, or a silicon resistance element.
3. (Original) A semiconductor device according to claim 1 or claim 2, wherein the sheet comprising the ferromagnetic material is formed by mixing soft magnetic powder and synthetic resin, then magnetized.
4. (Original) A semiconductor device comprising:
a support which is a binding material;
a protective film on the binding material;
a middle processing component comprising a control section and an operation section, and a memory unit on an insulating film adjacent to the binding material; and
the middle processing component includes a thin film transistor of n-channel type and a thin film transistor of p-channel type.

5. (Previously Presented) A semiconductor device according to any one of claims 1, 2, or 4, wherein the semiconductor device is an authentication card, a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, or a mobile information terminal.

6.-16. (Canceled)